FPF2000-FPF2007 IntelliMAX<sup>™</sup> Advanced Load Management Products



# FPF2000-FPF2007 IntelliMAX<sup>™</sup> Advanced Load Management Products

### Features

- 1.8 to 5.5V Input Voltage Range
- Controlled Turn-On
- 50mA and 100mA Current Limit Options
- Undervoltage Lockout
- Thermal Shutdown
- <1uA Shutdown Current</p>
- Auto restart
- Fast Current limit Response Time
  - 3us to Moderate Over Currents
  - 20ns to Hard Shorts
- Fault Blanking

# Applications

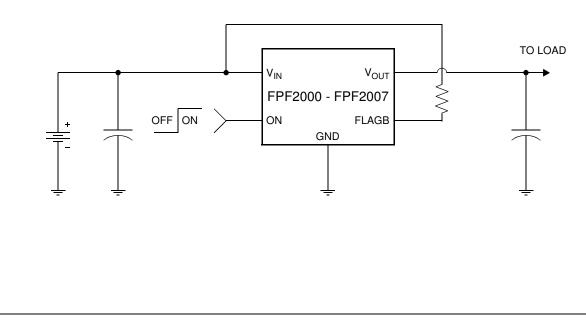
- PDAs
- Cell Phones
- GPS Devices
- MP3 Players
- Digital Cameras
- Peripheral Ports
- Hot Swap Supplies

# **General Description**

The FPF2000 through FPF2007 is a family of load switches which provide full protection to systems and loads which may encounter large current conditions. These devices contain a  $0.7\Omega$  current-limited P-channel MOSFET which can operate over an input voltage range of 1.8-5.5V. Switch control is by a logic input (ON) capable of interfacing directly with low voltage control signals. Each part contains thermal shutdown protection which shuts off the switch to prevent damage to the part when a continuous over-current condition causes excessive heating.

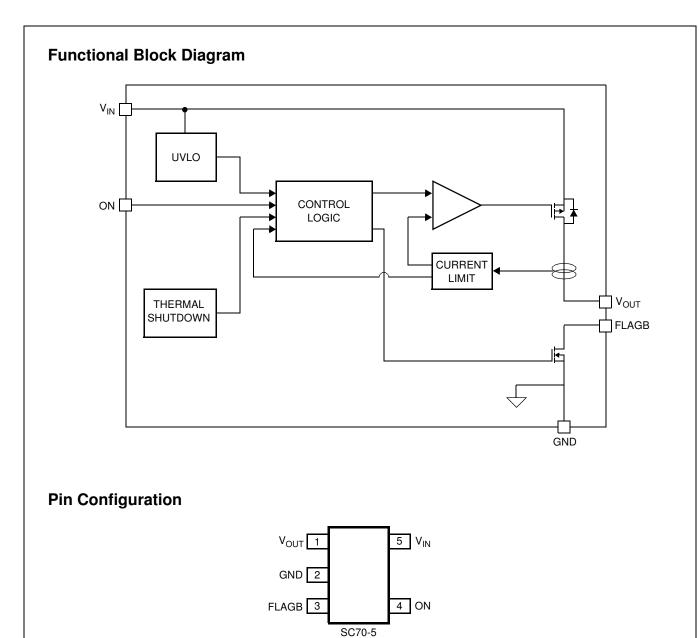
When the switch current reaches the current limit, the part operates in a constant current mode to prohibit excessive currents from causing damage. For the FPF2000-FPF2002 and FPF2004-FPF2006, if the constant current condition still persists after 10ms, these parts will shut off the switch and pull the fault signal pin (FLAGB) low. The FPF2000, FPF2001, FPF2004 and FPF2005, have an auto-restart feature which will turn the switch on again after 80ms if the ON pin is still active. The FPF2002 and FPF2006 do not have this auto-restart feature so the switch will remain off until the ON pin is cycled. For the FPF2003 and FPF2007, a current limit condition will immediately pull the fault signal pin low and the part will remain in the constant-current mode until the switch current falls below the current limit. For the FPF2000 through FPF2003, the minimum current limit is 50mA while that for the FPF2004 through FPF2007 is 100mA.

These parts are available in a space-saving 5 pin SC-70 package.



# **Typical Application Circuit**

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# **Pin Description**

Pin	Name	Function
1	V <sub>OUT</sub>	Switch Output: Output of the power switch
2	GND	Ground
3	FLAGB	Fault Output: Active LO, open drain output which indicates an over current, supply under voltage or over temperature state.
4	ON	On Control Input
5	V <sub>IN</sub>	Supply Input: Input to the power switch and the supply voltage for the IC

# **Absolute Maximum Ratings**

Parameter	Min.	Max.	Unit	
V <sub>IN</sub> , V <sub>OUT</sub> , ON, FLAGB to GND	-0.3	6	V	
Power Dissipation @ $T_A = 25 \degree C$ (note 1)		250	mW	
Operating Junction Temperature	-40	125	°C	
Storage Temperature	-65	150	°C	
Thermal Resistance, Junction to Ambient		400	°C/W	
Electrostatic Discharge Protection	HBM	4000		V
	MM	400		V

## **Recommended Operating Range**

Parameter	Min.	Max.	Unit	
V <sub>IN</sub>	1.8	5.5	V	
Ambient Operating Temperature, T <sub>A</sub>	-40	85	ç	

### **Electrical Characteristics**

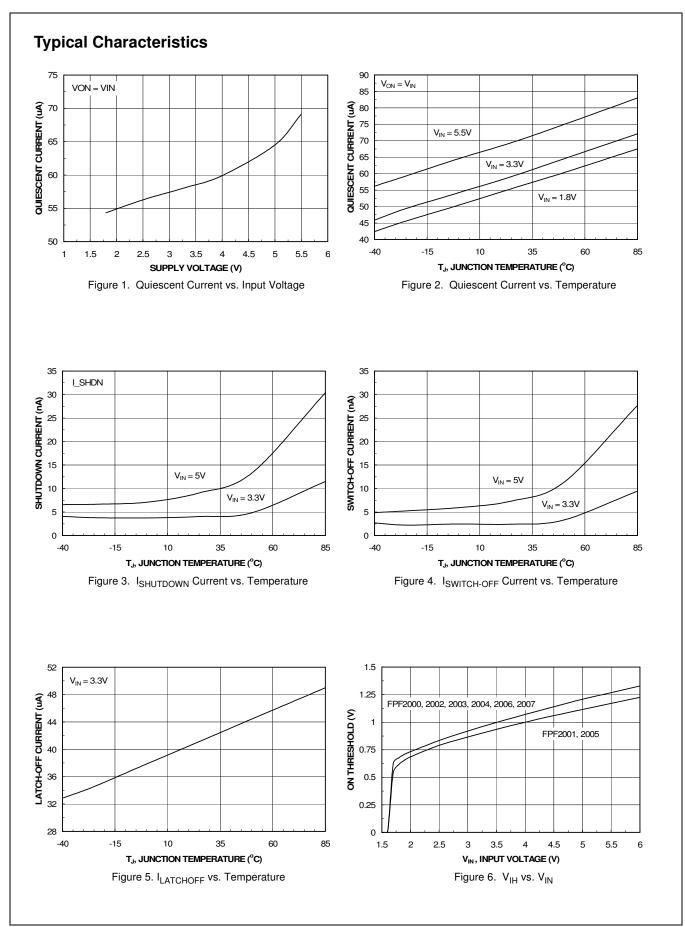
 $V_{IN}$  = 1.8 to 5.5V,  $T_A$  = -40 to +85 °C unless otherwise noted. Typical values are at  $V_{IN}$  = 3.3V and  $T_A$  = 25 °C.

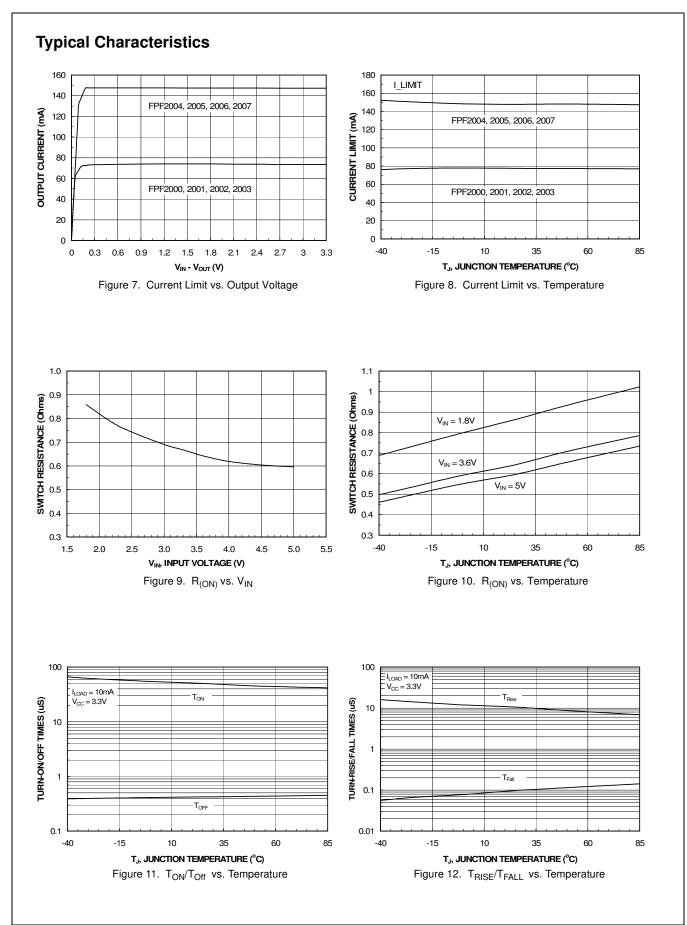
Parameter	Symbol	Conditions		Min.	Тур.	Max	Units
Basic Operation				I.			
Operating Voltage	V <sub>IN</sub>			1.8		5.5	V
Quiescent Current	l <sub>Q</sub>	I <sub>OUT</sub> = 0mA	V <sub>IN</sub> = 1.8 to 3.3V		60		μA
		Von active	V <sub>IN</sub> = 3.3 to 5.5V			100	
Shutdown Current	I <sub>SHDN</sub>					1	μA
Latch-Off Current (note 2)	I <sub>LATCHOFF</sub>	V <sub>ON</sub> = V <sub>IN</sub> , after	an overcurrent fault		40		μA
On-Resistance	R <sub>ON</sub>	T <sub>A</sub> = 25 °C, I <sub>OUT</sub>	= 20mA		0.7	1	Ω
		T <sub>A</sub> = -40 to +85 °C, I <sub>OUT</sub> = 20mA			0.85		
ON Input Logic High Voltage	V <sub>IH</sub>	V <sub>IN</sub> = 1.8V		0.8			V
		V <sub>IN</sub> = 5.5V		1.5			
ON Input Logic Low Voltage	V <sub>IL</sub>	V <sub>IN</sub> = 1.8V				0.5	V
		V <sub>IN</sub> = 5.5V				0.9	
ON Input Leakage		V <sub>ON</sub> = V <sub>IN</sub> or GND				1	μA
Off Switch Leakage	I <sub>SWOFF</sub>	$V_{ON} = 0V, V_{OUT} = 0V$				1	μA
FLAGB Output Logic Low Voltage		V <sub>IN</sub> = 5V, I <sub>SINK</sub> = 10mA			0.1	0.2	V
		V <sub>IN</sub> = 1.8V, I <sub>SINK</sub> = 10mA			0.1	0.3	
FLAGB Output High Leakage Current		V <sub>IN</sub> = 5V, Switch on				1	μA
Protections							
Current Limit	I <sub>LIM</sub>	V <sub>IN</sub> = 3.3V, V <sub>OUT</sub> = 3.0V	FPF2000, FPF2001, FPF2002, FPF2003	50	75	100	mA
			FPF2004, FPF2005, FPF2006, FPF2007	100	150	200	
Thermal Shutdown		Shutdown Three	shold		140		°C
		Return from Shutdown			130		
		Hysteresis			10		

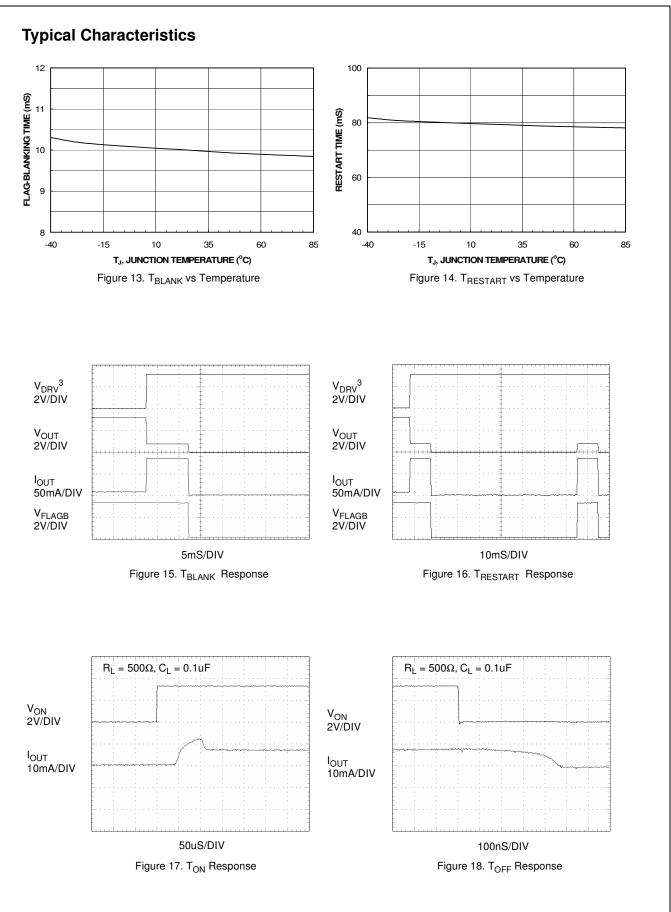
<b>Electrical Characteristics Cont.</b> $V_{IN} = 1.8$ to 5.5V, $T_A = -40$ to $+85$ °C unless otherwise noted. Typical values are at $V_{IN} = 3.3$ V and $T_A = 25$ °C.						
Protections		·				
Under Voltage Shutdown	UVLO	V <sub>IN</sub> Increasing	1.5	1.6	1.7	V
Under Voltage Shutdown Hysteresis				50		mV
Dynamic		·				
Turn on time	t <sub>ON</sub>	RL=500Ω, CL=0.1uF		50		μs
Turn off time	t <sub>OFF</sub>	RL=500Ω, CL=0.1uF		0.5		μs
V <sub>OUT</sub> Rise Time	t <sub>R</sub>	RL=500Ω, CL=0.1uF		10		μs
V <sub>OUT</sub> Fall Time	t <sub>F</sub>	RL=500Ω, CL=0.1uF		0.1		μs
ver Current Blanking Time t <sub>BLANK</sub>		FPF2000, FPF2001, FPF2002, FPF2004, FPF2005, FPF2006	5	10	20	ms
Auto-Restart Time t <sub>RSTRT</sub>		FPF2000, FPF2001, FPF2004, FPF2005	40	80	160	ms
Short Circuit Response Time		V <sub>IN</sub> = V <sub>ON</sub> = 3.3V. Moderate Over-Current Condition.		3		μs
		$V_{IN} = V_{ON} = 3.3V$ . Hard Short.		20		ns

Note 1: Package power dissipation on 1square inch pad, 2 oz copper board.

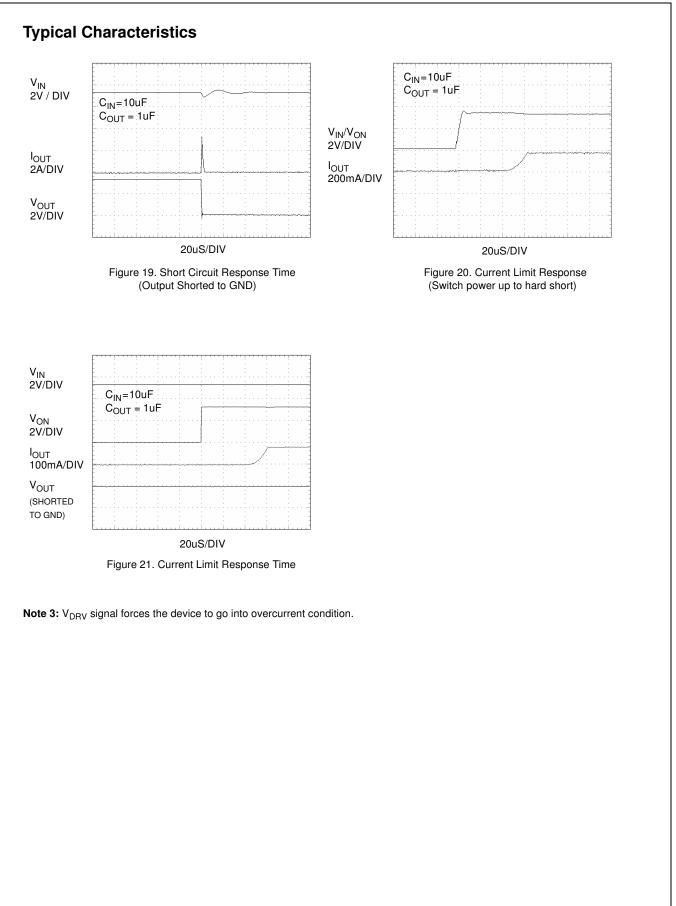
Note 2: Applicable only to FPF2002 and FPF2006. Latchoff current does not include current flowing into FLAGB.







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# **Description of Operation**

The FPF2000-FPF2007 are current limited switches that protect systems and loads which can be damaged or disrupted by the application of high currents. The core of each device is a  $0.7\Omega$ P-channel MOSFET and a controller capable of functioning over a wide input operating range of 1.8-5.5V. The controller protects against system malfunctions through current limiting, undervoltage lockout and thermal shutdown. The current limit is preset for either 50mA or 100mA.

## **On/OffControl**

The ON pin controls the state of the switch. Active HI and LO versions are available. Refer to the Ordering Information for details. Activating ON continuously holds the switch in the on state so long as there is no fault. For all versions, an under-voltage on VIN or a junction temperature in excess of 150 °C overrides the ON control to turn off the switch. In addition, excessive currents will cause the switch to turn off in FPF2000-FPF2002 and FPF2004-FPF2007. The FPF2000, FPF2001, FPF2004 and FPF2005 have an Auto-Restart feature which will automatically turn the switch on again after 80ms. For the FPF2002 and FPF2006, the ON pin must be toggled to turn-on the switch again. The FPF2003 and FPF2007 do not turn off in response to a over current condition but instead remain operating in a constant current mode so long as ON is active and the thermal shutdown or under-voltage lockout have not activated.

### Fault Reporting

Upon the detection of an over-current, an input under-voltage, or an over-temperature condition, the FLAGB signals the fault mode by activating LO. For the FPF2000-FPF2002 and FPF2004-FPF2006, the FLAGB goes LO at the end of the blanking time while FLAGB goes LO immediately for the FPF2003 and FPF2007. FLAGB remains LO through the Auto-Restart Time for the FPF2000, FPF2001 FPF2004 and FPF2005. For the FPF2002 and FPF2006, FLAGB is latched LO and ON must be toggled to release it. With the FPF2003 and FPF2007, FLAGB is LO during the faults and immediately returns HI at the end of the fault condition. FLAGB is an opendrain MOSFET which requires a pull-up resistor between VIN and FLAGB. During shutdown, the pull-down on FLAGB is disabled to reduce current draw from the supply.

# **Ordering Information**

#### **Current Limit** Auto-Restart **Current Limit Blanking Time** Time **ON Pin** Activity Part [mA] [ms] [ms] Top Mark FPF2000 50 10 80 Active HI 200 FPF2001 50 10 80 Active LO 201 FPF2002 50 10 NA Active HI 202 FPF2003 Active HI 50 0 NA 203 FPF2004 100 10 Active HI 204 80 FPF2005 100 10 80 205 Active LO FPF2006 100 10 NA Active HI 206 FPF2007 100 0 NA 207 Active HI

### Current Limiting

The current limit ensures that the current through the switch doesn't exceed a maximum value while not limiting at less than a minimum value. For the FPF2000-FPF2003 the minimum current is 50mA and the maximum current is 100mA and for the FPF2004-FPF2007 the minimum current is 100mA and the maximum current is 200mA. The FPF2000-FPF2002 and the FPF2004-FPF2006, have a blanking time of 10ms, nominally, during which the switch will act as a constant current source. At the end of the blanking time, the switch will be turned-off and the FLAGB pin will activate to indicate that current limiting has occurred. The FPF2003 and FPF2007 have no current limit blanking period so immediately upon a current limit condition FLAGB is activated. These parts will remain in a constant current state until the ON pin is deactivated or the thermal shutdown turns-off the switch.

### **Reverse Voltage**

If the voltage at the  $V_{\mbox{OUT}}$  pin is larger than the  $V_{\mbox{IN}}$  pin, large curents may flow and can cause permanent damage to the device. FPF2000-FPF2007 is designed to control current flow from V<sub>IN</sub> to V<sub>OUT</sub>.

### **Under-Voltage Lockout**

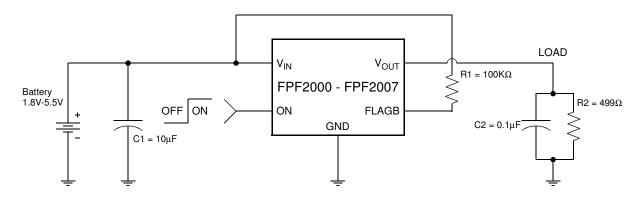
The under-voltage lockout turns-off the switch if the input voltage drops below the under-voltage lockout threshold. With the ON pin active the input voltage rising above the under-voltage lockout threshold will cause a controlled turn-on of the switch which limits current over-shoots.

### **Thermal Shutdown**

The thermal shutdown protects the die from internally or externally generated excessive temperatures. During an over-temperature condition the FLAGB is activated and the switch is turned-off. The switch automatically turns-on again if temperature of the die drops below the threshold temperature.

### **Application Information**

### **Typical Application**



### Input Capacitor

To limit the voltage drop on the input supply caused by transient in-rush currents when the switch turns-on into a discharged load capacitor or a short-circuit, a capacitor needs to be placed between V<sub>IN</sub> and GND. A 0.1 $\mu$ F ceramic capacitor, C<sub>IN</sub>, placed close to the pins is usually sufficient. Higher values of C<sub>IN</sub> can be used to further reduce the voltage drop.

#### **Output Capacitor**

A 0.1 $\mu$ F capacitor COUT, should be placed between V<sub>OUT</sub> and GND. This capacitor will prevent parasitic board inductances from forcing V<sub>OUT</sub> below GND when the switch turns-off. For the FPF2000-FPF2002 and the FPF2004-FPF2006, the total output capacitance needs to be kept below a maximum value, COUT(max), to prevent the part from registering an over-current condition and turning-off the switch. The maximum output capacitance can be determined from the following formula,

$$C_{OUT} = \frac{I_{LIM}(max) \times t_{BLANK}(min)}{V_{IN}}$$
(1)

Due to the integral body diode in the PMOS switch, a  $C_{\rm IN}$  greater than  $C_{\rm OUT}$  is highly recommended. A  $C_{\rm OUT}$  greater than  $C_{\rm IN}$  can cause  $V_{\rm OUT}$  to exceed  $V_{\rm IN}$  when the system supply is removed. This could result in current flow through the body diode from  $V_{\rm OUT}$  to  $V_{\rm IN}.$ 

#### **Power Dissipation**

During normal operation as a switch, the power dissipation is small and has little effect on the operating temperature of the part. The parts with the higher current limits will dissipate the most power and that will only be,

$$P = (I_{LIM})^2 \times R_{DS} = (0.2)^2 \times 0.7 = 28 \text{mW}$$
(2)

If the part goes into current limit the maximum power dissipation will occur when the output is shorted to ground. For the FPF2000, FPF2001, FPF2004 and FPF2005, the power dissipation will scale by the Auto-Restart Time,  $t_{\rm RESTART}$ , and the

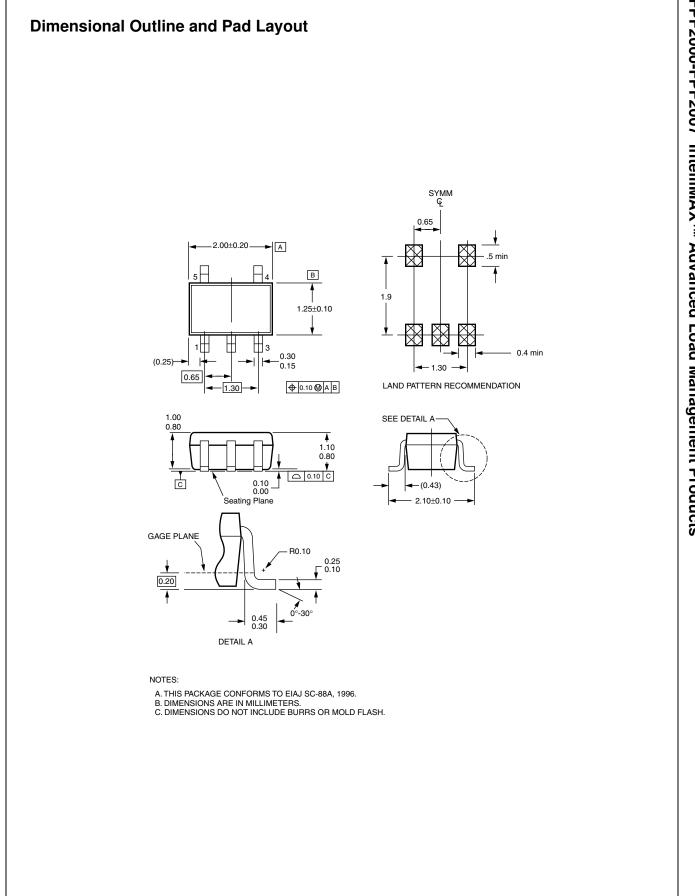
Over Current Blanking Time,  $t_{\mbox{\scriptsize BLANK}},$  so that the maximum power dissipated is,

$$P(max) = \frac{t_{BLANK}}{t_{RESTART} + t_{BLANK}} x(V_{IN(max)}) xI_{LIM(max)}$$
$$= \frac{10}{80 + 10} \times 5.5 \times 0.2 = 1.22 \text{mW}$$
(3)

When using the FPF2002 and FPF2006 attention must be given to the manual resetting of the part. Continuously resetting the part at a high duty cycle when a short on the output is present can cause the temperature of the part to increase. The junction temperature will only be allowed to increase to the thermal shutdown threshold. Once this temperature has been reached, toggling ON will not turn-on the switch until the junction temperature drops. For the FPF2003 and FPF2007, a short on the output will cause the part to operate in a constant current state dissipating a worst case power as calculated in (3) until the thermal shutdown activates. It will then cycle in and out of thermal shutdown so long as the ON pin is active and the short is present.

#### **Board Layout**

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effects that parasitic trace inductances may have on normal and short-circuit operation. Using wide traces for V<sub>IN</sub>, V<sub>OUT</sub> and GND will help minimize parasitic electrical effects along with minimizing the case to ambient thermal impedance.



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